



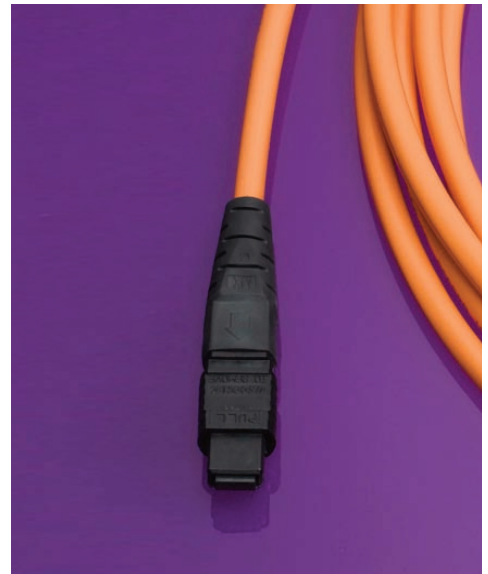
CXP optical cable assemblies from Molex offer improved fiber management for connecting CXP transceivers and complete Molex's iPass+ High-Speed Channel (HSC) CXP Copper and Optical System

Molex's low-profile CXP optical 4.50mm round cable assemblies offer improved fiber management over traditional flat cables for connecting CXP transceivers. The CXP optical cable assemblies utilize 24 fibers using industry-standard MTP/MPO connectors, 12 transmit (TX) and 12 receive (RX), and 10 Gbps high-bandwidth (OM3) fiber. This design meets the InfiniBand bandwidth requirements for CXP modules spaced up to 300.00m (984.25').

Molex provides a complete optical CXP solution with cable assemblies and loopbacks. Products include MTP/MPO-to-LC cable assemblies for connections to Small Form-factor Pluggable (SFP) or LC patch panels. Loopbacks feature a compact housing that loop optical TX to RX ports for testing, burn-in and field troubleshooting.

Molex's CXP optical cable assemblies are part of the iPass+ HSC CXP system, which is the latest addition to the existing iPass product family. The iPass Interconnect System offers connectors and cables that enable flexible-speed compatibility for applications ranging from 1 to 10 Gbps and is an ideal solution for the growing server-storage market. For additional information, visit: www.molex.com/link/cxp.html.

106284 Cable Assemblies



Features and Benefits

- MTP/MPO CXP connector interface meets CXP interface specifications
- Low-profile, round cable design for improved cable management over flat cable, with 360° cable-routing capability
- Up to 10 Gbps data rate capability provides optimized bandwidth by application
- RoHS compliant to meet environmental requirements for electronic equipment and accessories

SPECIFICATIONS

Reference Information

Packaging: Individual pack in a bag
Mates With: CXP Optical Transceivers

Optical

Fiber Specifications:

Fiber Count: 24 fibers (12 TX / 12 RX)

Multi Mode: 50/125µm

Insertion Loss at Test:

Multi Mode: 0.22dB Typical; ≤0.75dB max.

Connector to Connector: MTP to MTP

Bandwidth: See table on page 2 of datasheet

Mechanical

Bend Radius: 50.8mm (2.00") min. long-term

Physical

Jacket Dimensions:

Interconnect Cables — 1 to 20 meters: 4.50mm (.177")

Distribution Cables — 21 to 300 meters: 5.40mm (.213")

Fire Rating:

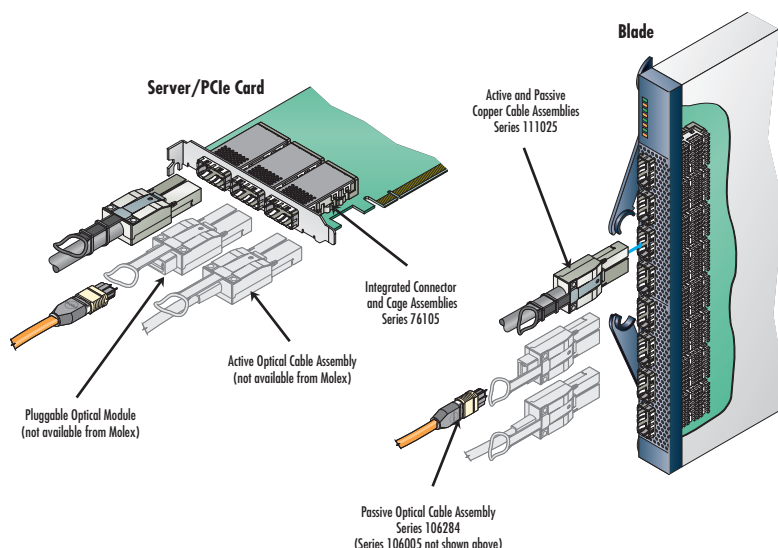
OFNR (Riser): Lengths less than or equal to 20 meters

OFNP (Plenum): Lengths over 20 meters

Operating Temperature: 0 to +70°C

Storage Temperature: -40 to +70°C

- **High-Performance Computing**
 - Controller cards and servers
 - Switches
 - Direct Attached Storage (DAS)
- **Data Centers**
 - Controller cards and servers
 - Switches
 - Blades
 - Storage Attached Networks (SAN)
- **Networking**
 - NIC cards and servers
 - Switches
 - Routers
 - Network Attached Storage (NAS)



BANDWIDTH SPEEDS

Fiber Type	Overfilled Launch Bandwidth, Min. (MHz-km)		1 Gigabit Ethernet Link Distance, Min. (m)		10 Gigabit Ethernet Link Distance, Min. (m)	
	850nm	1300nm	850nm	1300nm	850nm	1300nm
Standard Bandwidth	500	500	600	600	86	-
High Bandwidth	1500	500	900	550	300	-

ORDERING INFORMATION

Order No.	Bandwidth	Fire Rating	Cable Diameter	Length
106284-0001	Standard	OFNR (Riser)	4.50mm (.177")	1.00m (3.28')
106284-0005				5.00m (16.40')
106284-0010				10.00m (32.81')
106284-0015				15.00m (49.21')
106284-0020				20.00m (65.62')
106284-0025		OFNP (Plenum)	5.40mm (.213")	25.00m (82.02')
106284-0030				30.00m (98.43')
106284-0050				50.00m (164.04')
106284-0100				100.00m (328.08')
106284-1001	High (10 Gbps)	OFNR (Riser)	4.50mm (.177")	1.00m (3.28')
106284-1005				5.00m (16.40')
106284-1010				10.00m (32.81')
106284-1015				15.00m (49.21')
106284-1020				20.00m (65.62')
106284-1025		OFNP (Plenum)	5.40mm (.213")	25.00m (82.02')
106284-1030				30.00m (98.43')
106284-1050				50.00m (164.04')
106284-1100				100.00m (328.08')

www.molex.com/link/cxp.html

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В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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